

P16325

10/611,334

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of
John HECK

Serial No. 10/611,334 Group Art Unit: 2823

Filed: June 30, 2003 Examiner: LEE, Hsien Ming

For: MEMS PACKAGING USING A NON-SILICON SUBSTRATE
 FOR ENCAPSULATION AND INTERCONNECTION

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

AMENDMENT UNDER 37 C.F.R. § 1.111

Sir:

In response to the Office Action mailed on August 15, 2007, please
amend the above-identified application as follows: